

### **Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

### **Listing of Claims:**

1. (original) A polishing pad comprising:
  - a. a sublayer;
  - b. a middle layer; and
  - c. a top layer,wherein said top layer is at least partially connected to said middle layer and said middle layer is at least partially connected to said sublayer, and wherein said top layer absorbs at least two percent by weight of polishing slurry based on total weight of said top layer.
2. (original) The polishing pad of claim 1 wherein said top layer absorbs 50% or less by weight of polishing slurry based on total weight of said top layer.
3. (original) The polishing pad of claim 1 wherein said top layer is selected from particulate polymer and crosslinked polymer binder; particulate polymer and an organic polymer binder; sintered particles of thermoplastic resin; pressure sintered powder compacts of thermoplastic polymer; polymeric matrices impregnated with a plurality of polymeric microelements wherein each polymeric microelement can have a void space therein, or combinations thereof.
4. (original) The polishing pad of claim 1 wherein said top layer has a thickness of at least 0.020 inches.
5. (original) The polishing pad of claim 4 wherein said top layer has a thickness of 0.150 inches or less.
6. (original) The polishing pad of claim 1 wherein said top layer further comprises grooves in a polishing surface.
7. (original) The polishing pad of claim 1 wherein said top layer further comprises a pattern in a polishing surface.
8. (original) The polishing pad of claim 1 wherein said middle layer is selected from substantially non-volume compressible polymers and metallic films and foils.
9. (original) The polishing pad of claim 1 wherein said middle layer is selected from polyolefins; cellulose-based polymers; acrylics; polyesters and co-polyesters; polycarbonate; polyamides; high performance plastics; or mixtures thereof.

10. (original) The polishing pad of claim 1 wherein said middle layer is selected from low density polyethylene, high density polyethylene ultra-high molecular weight polyethylene or polypropylene; cellulose acetate or cellulose butyrate; PET or PETG; nylon 6/6 or nylon 6/12; polyetheretherketone, polyphenylene oxide, polysulfone, polyimide, or polyetherimide; or mixtures thereof.
11. (original) The polishing pad of claim 1 wherein said middle layer has a thickness of at least 0.0005 inches.
12. (original) The polishing pad of claim 11 wherein said middle layer has a thickness of 0.0030 inches or less.
13. (original) The polishing pad of claim 1 wherein said sublayer is selected from natural rubber, synthetic rubbers, thermoplastic elastomer, foam sheet and combinations thereof.
14. (original) The polishing pad of claim 1 wherein said sublayer has a thickness of at least 0.020 inches.
15. (original) The polishing pad of claim 14 wherein said sublayer has a thickness of 0.100 inches or less.
16. (original) The polishing pad of claim 1 wherein said sublayer, middle layer and top layer are at least partially connected by an adhesive material.
17. (original) The polishing pad of claim 16 wherein said adhesive material is selected from contact adhesives, pressure sensitive adhesives, structural adhesives, hot melt adhesives, thermoplastic adhesives, and curable adhesives, thermosetting adhesives; and combinations thereof.
18. (original) The polishing pad of claim 1 wherein said sublayer has a percent volume compressibility that is greater than the top layer.
19. (original) The polishing pad of claim 18 wherein said percent volume compressibility of said sublayer is less than 20% when a load of 20 psi is applied.
20. (original) The polishing pad of claim 18 wherein said percent volume compressibility of the top layer is 3% or less when a load of 20 psi is applied.
21. (original) The polishing pad of claim 1 wherein said middle layer is substantially non-volume compressible.
22. (original) The polishing pad of claim 1 wherein said middle layer has a flexibility of at least  $1 \text{ in}^{-1} \text{ lb}^{-1}$ .
23. (original) The polishing pad of claim 1 wherein said middle layer comprises an adhesive assembly.

24. (original) A polishing pad comprising:
- a. a sublayer;
  - b. a middle layer; and
  - c. a top layer,
- wherein said top layer is at least partially connected to said middle layer and said middle layer is at least partially connected to said sublayer, and wherein said top layer has a porosity of at least two percent by volume based on total volume of said top layer.
25. (original) The polishing pad of claim 24 wherein said top layer has a porosity of 50% or less by volume based on total volume of said top layer.
26. (original) The polishing pad of claim 24 wherein said top layer is selected from particulate polymer and crosslinked polymer binder; particulate polymer and an organic polymer binder; sintered particles of thermoplastic resin; pressure sintered powder compacts of thermoplastic polymer; polymeric matrices impregnated with a plurality of polymeric microelements wherein each polymeric microelement can have a void space therein, or combinations thereof.
27. (original) The polishing pad of claim 24 wherein said top layer has a thickness of at least 0.020 inches.
28. (original) The polishing pad of claim 27 wherein said top layer has a thickness of 0.150 inches or less.
29. (original) The polishing pad of claim 24 wherein said top layer further comprises grooves in a polishing surface.
30. (original) The polishing pad of claim 24 wherein said top layer further comprises a pattern in a polishing surface.
31. (original) The polishing pad of claim 24 wherein said middle layer is selected from substantially non-volume compressible polymers and metallic films and foils.
32. (original) The polishing pad of claim 24 wherein said middle layer is selected from polyolefins; cellulose-based polymers; acrylics; polyesters and co-polyesters; polycarbonate; polyamides; high performance plastics; or mixtures thereof.
33. (original) The polishing pad of claim 1 wherein said middle layer is selected from low density polyethylene, high density polyethylene ultra-high molecular weight polyethylene or polypropylene; cellulose acetate or cellulose butyrate; PET or

PETG; nylon 6/6 or nylon 6/12; polyetheretherketone, polyphenylene oxide, polysulfone, polyimide, or polyetherimide; or mixtures thereof.

34. (original) The polishing pad of claim 24 wherein said middle layer has a thickness of at least 0.0005 inches.
35. (original) The polishing pad of claim 34 wherein said middle layer has a thickness of 0.0030 inches or less.
36. (original) The polishing pad of claim 24 wherein said sublayer is selected from natural rubber, synthetic rubbers, thermoplastic elastomer, foam sheet and combinations thereof.
37. (original) The polishing pad of claim 24 wherein said sublayer has a thickness of at least 0.020 inches.
38. (original) The polishing pad of claim 37 wherein said sublayer has a thickness of 0.100 inches or less.
39. (original) The polishing pad of claim 34 wherein said sublayer, middle layer and top layer are at least partially connected by an adhesive material.
40. (original) The polishing pad of claim 39 wherein said adhesive material is selected from contact adhesives, pressure sensitive adhesives, structural adhesives, hot melt adhesives, thermoplastic adhesives, curable adhesives, thermosetting adhesives and combinations thereof.
41. (original) A polishing pad comprising:
  - a. a sublayer;
  - b. a middle layer; and
  - c. a top layer,wherein said sublayer is at least partially connected to said middle layer and said middle layer is at least partially connected to said top layer, and wherein said top layer has a percent volume compressibility greater than said middle layer.
42. (original) The polishing pad of claim 41 wherein said top layer has a percent volume compressibility of at least 0.3% when a load of 20 psi is applied.
43. (original) The polishing pad of claim 42 wherein said top layer has a percent volume compressibility of 3% or less when a load of 20 psi is applied.
44. (original) The polishing pad of claim 41 wherein said middle layer is substantially non-volume compressible.
45. (original) The polishing pad of claim 41 wherein said middle layer has a percent volume compressibility of at least 1 percent when a load of 20 psi is applied.

46. (original) The polishing pad of claim 41 wherein said middle layer has a percent volume compressibility of 3 percent or less when a load of 20 psi is applied.
47. (original) The polishing pad of claim 41 wherein said top layer is selected from particulate polymer and crosslinked polymer binder; particulate polymer and an organic polymer binder; sintered particles of thermoplastic resin; pressure sintered powder compacts of thermoplastic polymer; polymeric matrices impregnated with a plurality of polymeric microelements wherein each polymeric microelement can have a void space therein, or combinations thereof
48. (original) The polishing pad of claim 41 wherein said top layer has a thickness of at least 0.020 inches.
49. (original) The polishing pad of claim 48 wherein said top layer has a thickness of 0.150 inches or less.
50. (original) The polishing pad of claim 41 wherein said top layer further comprises grooves in a polishing surface.
51. (original) The polishing pad of claim 41 wherein said top layer further comprises a pattern in a polishing surface.
52. (original) The polishing pad of claim 41 wherein said middle layer is selected from substantially non-volume compressible polymers and metallic films and foils.
53. (original) The polishing pad of claim 41 wherein said middle layer is selected from polyolefins; cellulose-based polymers; acrylics; polyesters and co-polyesters; polycarbonate; polyamides; high performance plastics; or mixtures thereof.
54. (original) The polishing pad of claim 41 wherein said middle layer is selected from low density polyethylene, high density polyethylene ultra-high molecular weight polyethylene or polypropylene; cellulose acetate or cellulose butyrate; PET or PETG; nylon 6/6 or nylon 6/12; polyetheretherketone, polyphenylene oxide, polysulfone, polyimide, or polyetherimide; or mixtures thereof.
55. (original) The polishing pad of claim 41 wherein said middle layer comprises an adhesive assembly.
56. (original) The polishing pad of claim 41 wherein said middle layer has a thickness of at least 0.0005 inches.
57. (original) The polishing pad of claim 56 wherein said middle layer has a thickness of 0.0030 inches or less.

58. (original) The polishing pad of claim 41 wherein said sublayer is selected from natural rubber, synthetic rubbers, thermoplastic elastomer, foam sheet and combinations thereof.
59. (original) The polishing pad of claim 41 wherein said sublayer has a thickness of at least 0.020 inches.
60. (original) The polishing pad of claim 59 wherein said sublayer has a thickness of 0.100 inches or less.
61. (original) The polishing pad of claim 41 wherein said sublayer, middle layer and top layer are at least partially connected by an adhesive material.
62. (original) The polishing pad of claim 61 wherein said adhesive material is selected from contact adhesives, pressure sensitive adhesives, structural adhesives, hot melt adhesives, thermoplastic adhesives, curable adhesives, thermosetting adhesives and combinations thereof.
63. (original) A polishing pad comprising:
- a. a sublayer;
  - b. a middle layer; and
  - c. a top layer,
- wherein said sublayer is at least partially connected to said middle layer and said middle layer is at least partially connected to said top layer, and wherein said sublayer is softer than said top layer.
64. (original) A method of preparing a polishing pad comprising at least partially connecting a top layer to a middle layer; and at least partially connecting said middle layer to a sublayer, wherein said top layer absorbs at least two percent by weight of polishing slurry based on total weight of said top layer.
65. (original) The method of claim 64 wherein said top, middle and sub layers are at least partially connected by an adhesive material.
66. (original) A method of preparing a polishing pad comprising at least partially connecting a top layer to a middle layer; and at least partially connecting said middle layer to a sublayer, wherein said top layer has a porosity of at least two percent by volume based on total volume of said top layer.
67. (original) The method of claim 66 wherein said top, middle and sub layers are at least partially connected by an adhesive material.
68. (original) A method of preparing a polishing pad comprising at least partially connecting a top layer to a middle layer; and at least partially connecting said

middle layer to a sublayer, wherein said wherein said top layer has a percent volume compressibility greater than said middle layer.

69. (original) The method of claim 68 wherein said top, middle and sub layers are at least partially connected by an adhesive material.